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OverView

Specifications

Model	IIM-3000
Target Wafer	Φ 300 ㎜ Si Wafer (Polished, Etched) / N, P-, P+, P++
Detectable Defects	Buried–Airpocket, Surface Bump, Through–Hole
Min. Detectable Airpocket	APK ≥ 20 ㎛ diameter Capture Rate (DSP): ≥ 95 % for 25 ㎛ APK Capture Rate (Ground): ≥ 95 % for 30 ㎛ APK
Defect Information	Diameter, Long-Short Ratio, Circularity X,Y,Z coordinate (Z means the depth of defect)
Throughput	120 Wfrs/h
Dimension	1450 ㎜ (W) x 2300 ㎜ (D) x 2010 ㎜ (H)
Weight	1300 Kg

OverView

- IIM-3000 is a equipment that detects all defects and measures the size of each defect on 300 mm Si wafers. Followings are the types of defects that IIM-3000 can detect ; Buried airpockets, Bumps and Through-holes.
- The advanced defect detection and classification algorithms, enable users to detect easily all defects in various Si wafers(N. P-, P +, P ++) with high throughput.
- A specialized controller for IIM-3000 provides the optimized control unit, which enables easy maintenance and quick setup.

- By applying optimized software, IIM-3000 provides reliable inspection quality and result data for users also.

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